

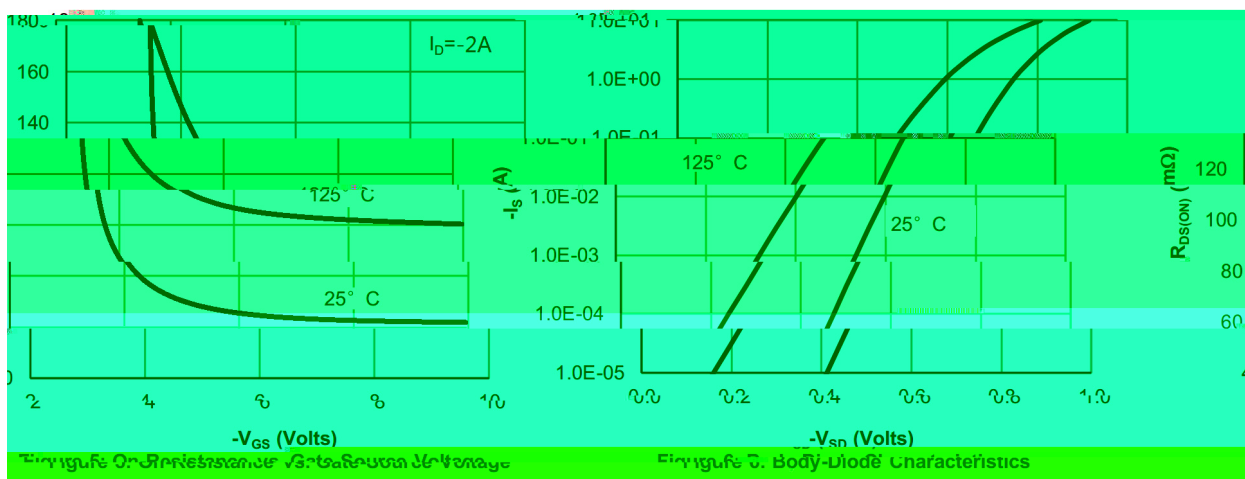
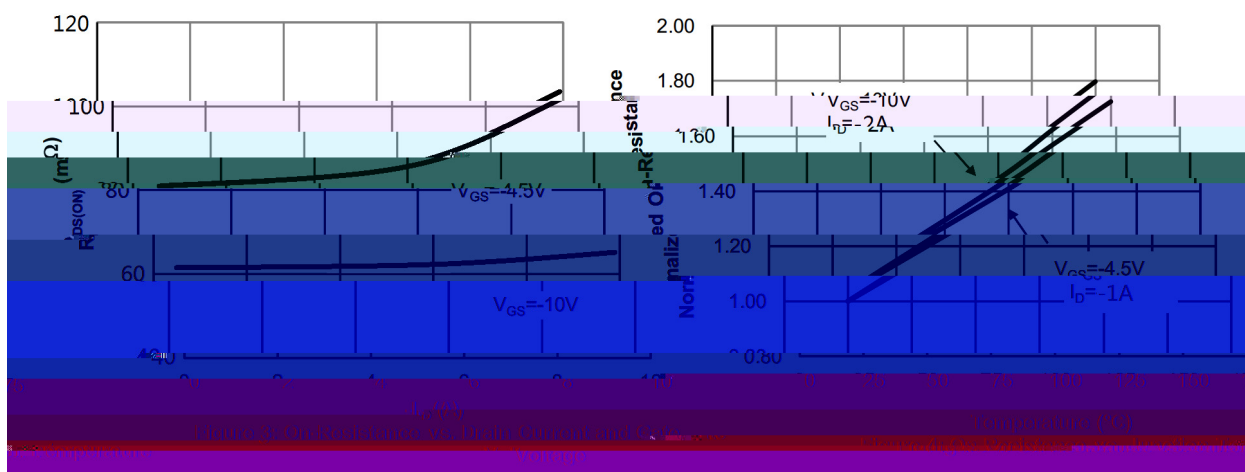
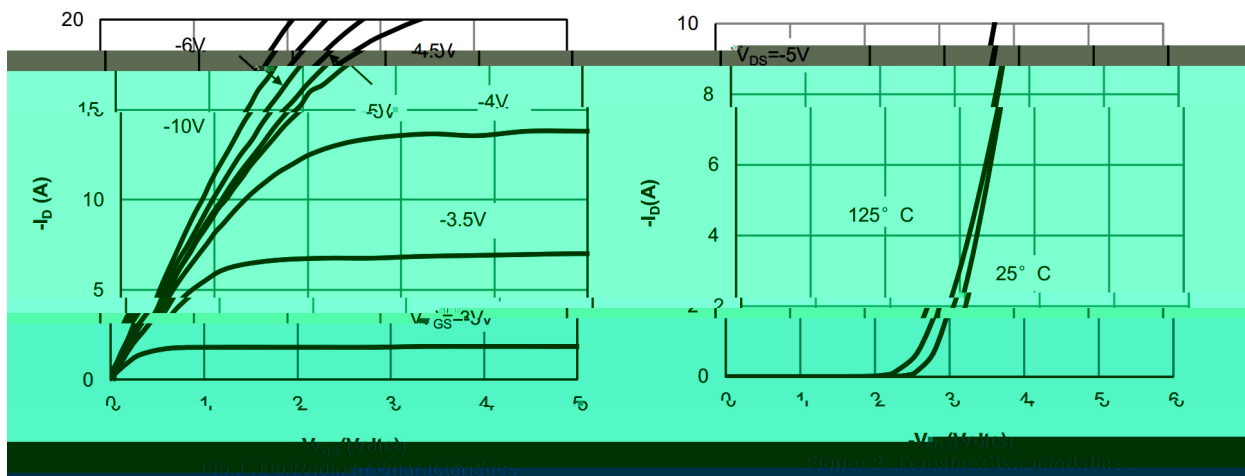
Parameter		Symbol	Rating	Unit
Drain–Source Voltage		V_{DS}	-60	V
Gate–Body Leakage Voltage		V_{GSS}	± 20	V
Drain Current - Continuous		I_D	-6	A
Power Dissipation (Surface Mounted on FR4 Board, $t \leq 10$ sec.)		P_D	5.3	W
Operating and Storage Temperature Range		T_J, T_{STG}	-55~150	
Maximum Junction-to-Ambient	$t \leq 10s$	$R_{\theta JA}$	40	$^{\circ}C/W$
Maximum Junction-to-Ambient	Steady-State		75	$^{\circ}C/W$
Maximum Junction-to-Lead	Steady-State	$R_{\theta JL}$	23.5	$^{\circ}C/W$

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain–Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V$ $I_D=-250\mu A$	-60	-71		V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ $I_D=-250\mu A$	-1	-2.1	-3	V
Static Drain–Source On–Resistance	$R_{DS(on)}$	$V_{GS}=-10V$ $I_D=-2A$		61	80	m Ω
		$V_{GS}=-4.5V$ $I_D=-1A$		77	120	m Ω
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-60V$ $V_{GS}=0V$			-1.0	μA
Gate–Body Leakage.	I_{GSS}	$V_{GS}=-20V$			-100	nA
		$V_{GS}=20V$			100	nA
Drain-Source Diode Forward Voltage	V_{SD}	$V_{GS}=0V$ $I_S=-1A$ $T_J=25$			-1.2	V
Input Capacitance	C_{iss}	$V_{DS}=-25V$ $V_{GS}=0V$ $f=1.0MHz$		1600		pF
Output Capacitance	C_{oss}			400		
Reverse Transfer Capacitance	C_{rss}			300		
Total Gate Charge	$Q_{g(10V)}$	$V_{DS}=-30V$ $V_{GS}=-10.0V$ $I_D=-4A$		18		nC
Total Gate Charge	$Q_{g(4.5V)}$			9.1		
Gate-to-Source Charge	Q_{gs}			2.7		
Gate-to-Drain Charge	Q_{gd}			3.1		
Turn–On Delay Time	$t_{d(on)}$					

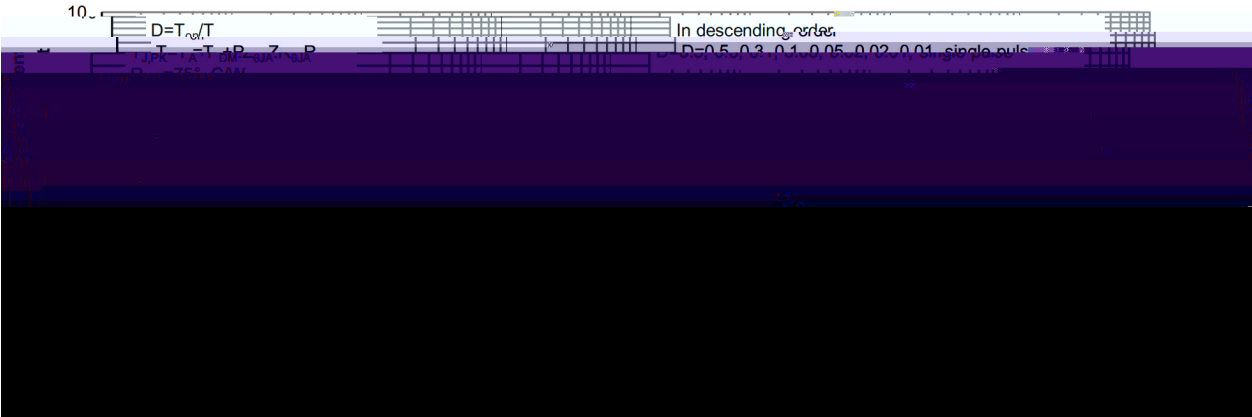
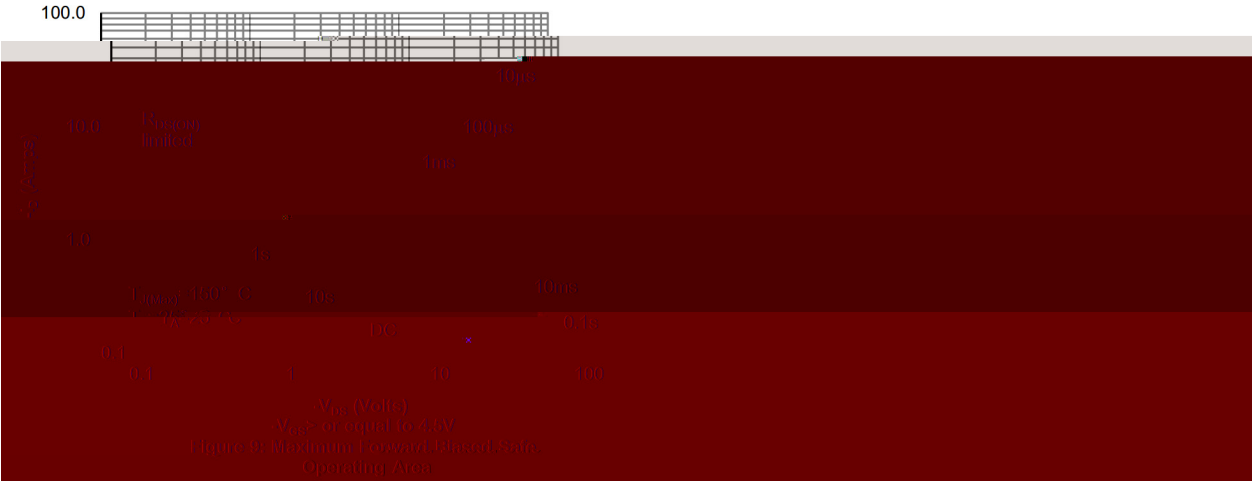
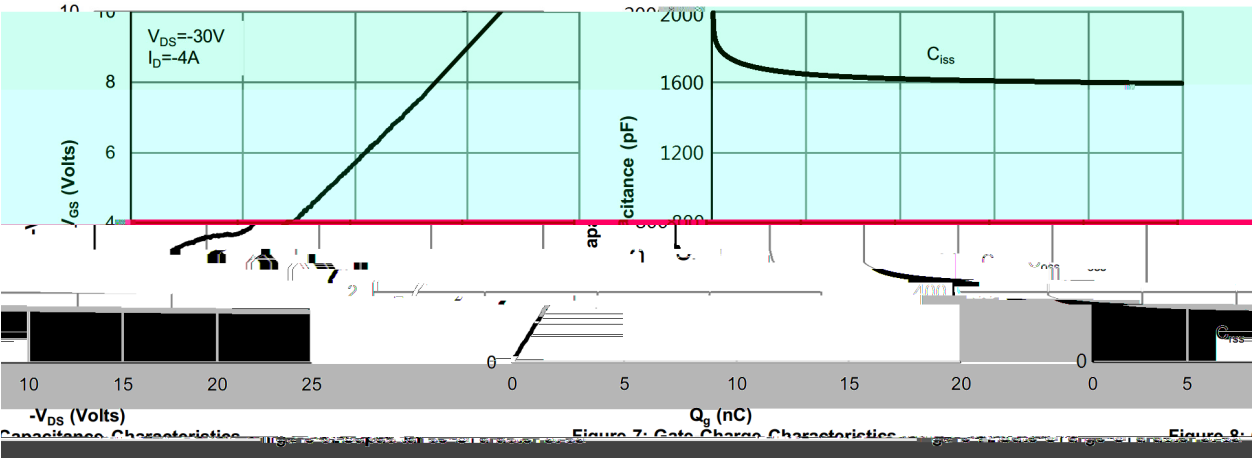
 $V_{DD}=-30V$ V_{GS}



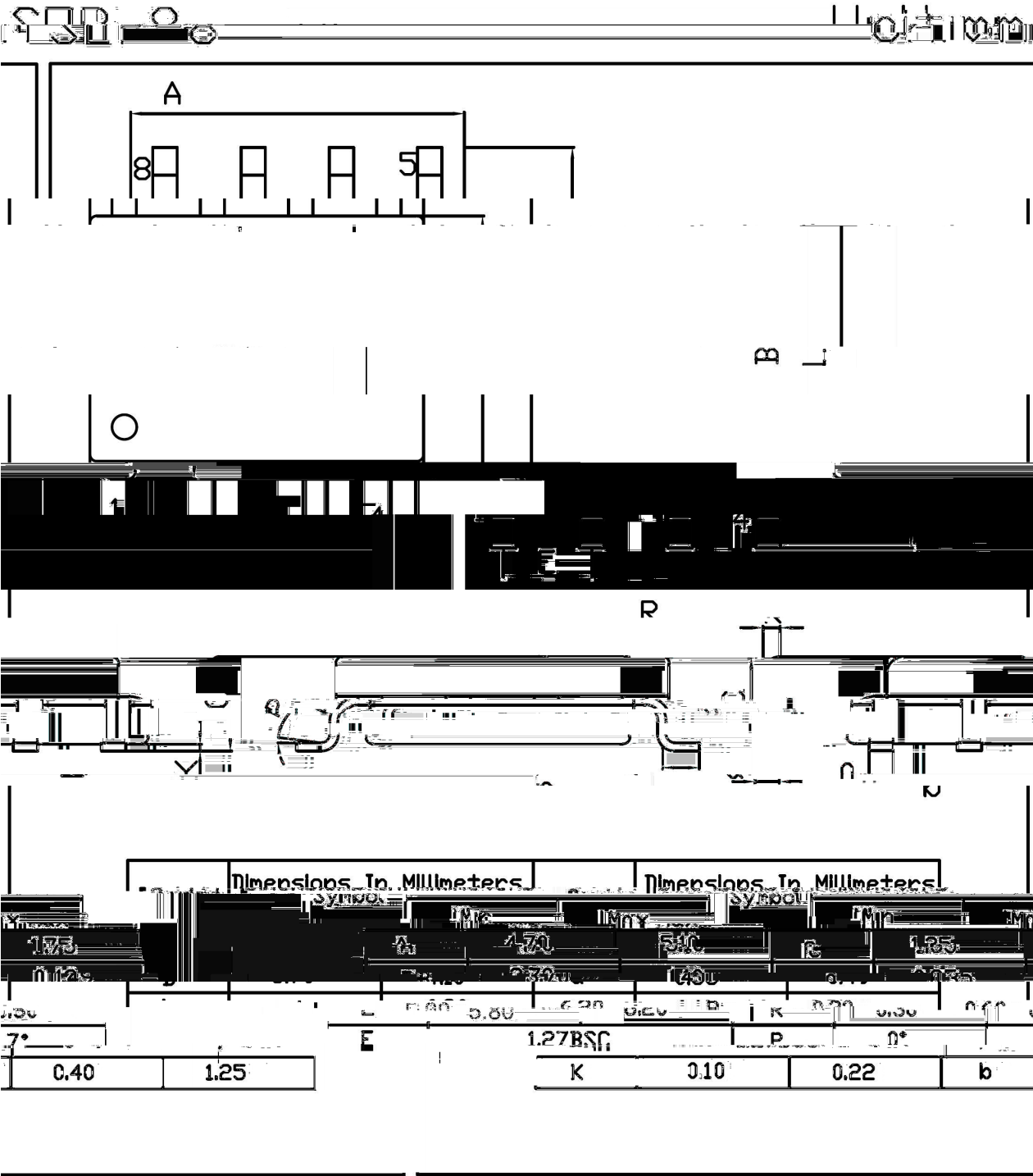
/ Electrical Characteristic Curve



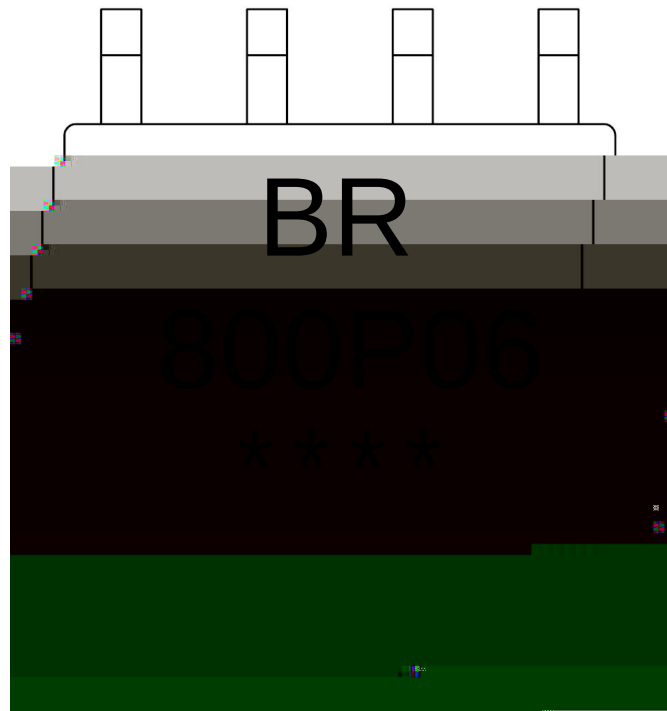
/ Electrical Characteristic Curve



/ Package Dimensions



/ **Marking Instructions**



BR

800P06

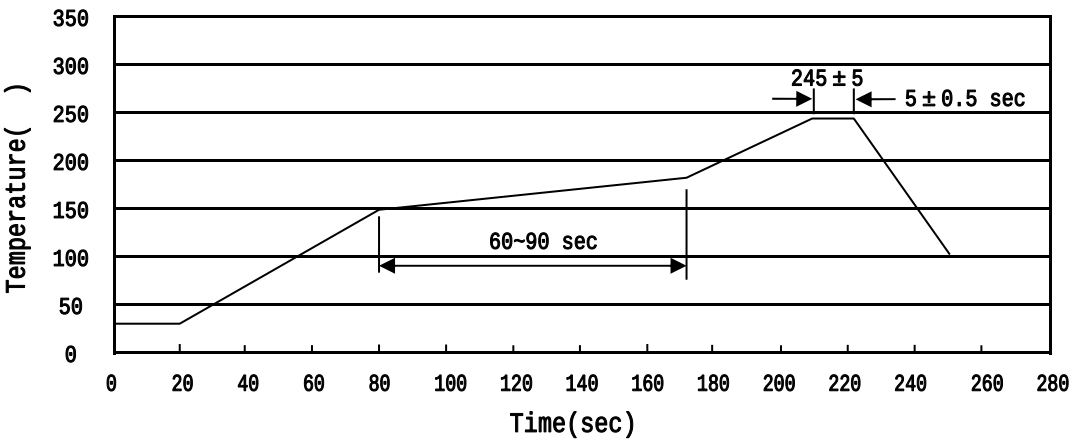
Note:

BR: Company Code

800P06: Product Type

****: Lot No. Code, code change with Lot No

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- 1

150 180

60 90sec;
- 2

245±5

5±0.5sec;
- 3

2 10 /sec.
- 1.Preheating:150~180

, Time:60~90sec.
- 2.Peak Temp.:245±5

, Duration:5±0.5sec.
3. Cooling Speed: 2~10

/sec.

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm ³)		
SOP/ESOP-8	4,000	2	8,000	6	48,000	13 ×12	360×360×50	380×335×366

/ Notices